

Docket No.: YOR9200030587US1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Cyril Cabral, Jr. et al.

Application No.: 10/714,966

Confirmation No.: 4605

Filed: November 18, 2003

Art Unit: 2811

For: ELECTROPLATED COWP COMPOSITES
STRUCTURES AS COPPER BARRIER LAYERS

Examiner: H. K. Vu

COMMUNICATION

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicant filed a Response to Final Action under 37 C.F.R. 1.116 on October 30, 2006. However, the electronic signature was inadvertently omitted. Therefore, please accept this Response to Final Office Action with the proper electronic signature.

Applicant believes no fee is due with this response. However, if a fee is due, please charge our Deposit Account No. 50-0510, under Order No. 20140-00308-US1 from which the undersigned is authorized to draw.

Dated: October 30, 2006

Respectfully submitted,

By /Donald K. Drummond/
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